

06-Oct	Professional Development Courses		
09:00	registration		
10:00	PDC 1	ESA	Working with ESA: EEE sovereignty, qualification, technology development funding
11:00	break		
11:30	PDC 2	placeholder	Advanced packaging
13:00	lunch		
14:00	PDC 3	Spacechips, Rajan Bedi	Flexible PCB Design and Manufacturing for Space Applications
15:00	break		
15:20	PDC 4	Spacechips, Rajan Bedi	Right-First-Time Design for Fabrication and Assembly Considerations When Manufacturing Space-Grade PCBs
16:20	break		
16:40	PDC 5	ESA	Space mission classification and the materials & processes control board
17:40	end		
7, 8 Oct	Poster presentations during afternoon breaks		
46	Sapienza University Of Rome, Simone Bandini		Morphological and Compositional Evolution of InPb/Au Solder Joints under Thermal Ageing in Atmospheric and Vacuum Environments
47	Manchester Metropolitan University, Sunday Enahoro		Digital Twin-Enabled Design and Sustainability Assessment of mmWave Energy Harvesting Antennas for Satellite and IoT Applications
48	HTV Conservation GmbH, Thorsten Leist		Quality assurance of additively manufactured electronics
49	DSI Aerospace, Jan Frederik Wagenfeld		PCB Design Challenges in Next-Generation Space Mass Memory Units

07-Oct					
08:00		registration			
09:00		ESA	Welcome		
09:10		Global Electronics Association	The path towards Advanced Electronic Packaging		
09:20	1	additive manufactured electronics	Advanced Technology Institute, University Of Surrey, Jose Anguita	Compact System for Printing Electronics with Potential for Space Applications	
09:45	2		Politecnico di Milano, Andrea Mistrini	Laser Additive Manufacturing of High-Performance Thermal Management Systems for Aerospace High-Power Electronics	
10:10	3		Holst Centre - Tno, Darragh Walsh	Novel Additive Manufacturing Platform for Freeform 3D Microelectronics and Packaging	
10:35	4		Jadavpur University, Soham Ghosh	Design of Scalp-Implantable and Non-Invasive Antenna System for Intracranial Pressure Monitoring	
11:00		break			
11:30	5	PCB 1	Alter Technology, Mari Carmen López	Critical Role of Tg and CTE Characterization in PCB Design Using Thermomechanical Analysis (TMA)	
11:55	6		Hytek, Poul Juul	Physical characterization of PCB materials	
12:20	7		Istituto Italiano Della Saldatura, Luca Moliterni	Study of Base Laminates Used for High Reliability Printed Circuits Boards	
12:45	8		LPKF Laser & Electronics, Patrick Stockbrügger	Potential of laser depaneling for harsh environments in terms of quality and reliability	
13:10		lunch			
14:10	9	lead-free assembly	Nanospace, Pascale Wiesmann	Lead-free assembly technologies for telecom satellite equipment (ESA ARTES)	
14:35	10		Technical University of Darmstadt, Guillaume Meyer	Lead-Free Transition for the European Space Sector - the Tin Whiskers Challenge	
15:00	11		Spur Electron, Cathy Chandler	Lead-free assembly technologies for telecom satellite equipment	
15:25	12		Teledyne E2v, Eric Perriaud	Board Level Reliability Testing of BGA Packages Equipped with Lead-Free Interconnection Solutions and Dedicated to Space Applications	
15:50		break			
16:20		13	modelling	Hooke Electronics, Jean-Baptiste Libot	Physics-of-Failure Based Reliability Modeling of Lead-Free Electronic Assemblies Under Thermal Cycling
16:45		14		Schaeffler, Nicolae Badulescu	Approach for Coupled Simulations of Magnetic Power Loss and Temperature Distribution of a DC/DC Converter Used for Electric Vehicles
17:10		15		Imec, Klara Volckaert	Experimental Data-Driven Prediction of Input Parameters for Finite Element Simulations for Electronic Assemblies
17:35		end			
18:00		welcome reception at Space EXPO			
20:00		end			

